

Migrating from MX60LF8G18AC to MX60LF8G28AD

1. Introduction

This application note is a guide for migrating Macronix NAND device from the MX60LF8G18AC to the MX60LF8G28AD. Both NAND devices are 8Gb SLC NAND Flash built with two stacked 4Gb chips. The document does not provide detailed information on the individual devices, but highlights the major similarities and differences between them. The comparison covers the general features, performance, command codes and other differences.

The information in this document is based on datasheets listed in Section 8. Newer versions of the datasheets may override the contents of this document.

2. General Features

With the exception of some additional features of the MX60LF8G28AD, such as "Randomizer", "Special read for data recovery", and the different page/spare/block size, both flash devices have similar features and functions as shown in **Table 2-1**. Feature differences are highlighted in **Bold Italic** type in the table.

Table 2-1. Key Features Comparison

Part Name	MX60LF8G18AC	MX60LF8G28AD	
Voltage	2.7V-3.6V	2.7V-3.6V	
Bus Width	x8	x8	
Operating Temperature	-40°C to 85°C	-40°C to 85°C	
Interface	ONFI 1.0 Compliant	ONFI 1.0 Compliant	
Page Size	(2K+64)B	(4K+256)B	
Block Size	(128K+4K)B	(256K+16K)B	
ECC Requirement	4 bit/528B	8bit/ 544 B	
Interleaved Die Operations	Supported	Supported	
Cache Read/ Cache Program	ONFI Standard	ONFI Standard	
ОТР	30 Pages	30 Pages	
Unique ID	ONFI Standard	ONFI Standard (PUF type) ^{note}	
Randomizer	N/A	Supported	
Special Read for Data Recovery	N/A	Supported	
Guaranteed Good Blocks at Shipping	Block#0	Block#0-7	
Data Retention	10 Years	10 Years	
Endurance	100K Cycles	60K Cycles	
Package	48TSOP (12x20mm) 63-VFBGA (9x11mm)	48TSOP (12x20mm) 63-VFBGA (9x11mm)	

Note: PUF (physical unclonable function)

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3. Electrical Performance

The key performance specifications are similar for the two devices. Performance differences are highlighted in Bold Italic type in **Table 3-1**.

Table 3-1. Key Performance Comparison

Part Name		MX60LF8G18AC		MX60LF8G28AD			
Performance		Min.	Тур.	Max.	Min.	Тур.	Max.
	Random (tR)	-	-	25us	-	-	25us
Access Time	Cache Read Busy time	-	2us	25us	-	4.5us	25us
	Sequential	20ns	-	-	20ns	-	-
	Page Program	-	300us	600us	-	320us	700us
Program Time	Cache Program Busy time	-	3us	600us	-	5us	700us
Erase Time	Block	-	1ms	3.5ms	-	4ms	6ms
	Standby (TTL)	-	-	2mA	-	-	2mA
	Standby (CMOS)	-	20uA	100uA	-	20uA	100uA
	Active Read	-	20mA	30mA	-	20mA	30mA
	Active Program	-	20mA	30mA	-	20mA	30mA
Current Consumption	Active Erase	-	15mA	30mA	-	15mA	30mA
	Power-up Current (Including POR Current)	-	-	60mA	-	-	50mA
	Input Leakage	-	-	+/- 20uA	-	-	+/- 20uA
	Output Leakage	-	-	+/- 20uA	ı	-	+/- 20uA
Partial-Page Programs	NOP	-	-	4 cycles	-	-	4 cycles



4. Command Set

The command set is the same for the two devices (Table 4-1 Command Set).

Table 4-1. Command Set

Part Name	MX60LF8G18AC		MX60LF	8G28 <i>AD</i>
Command Description	1st Command	2nd Command	1st Command	2nd Command
·	Cycle	Cycle	Cycle	Cycle
Read	00h	30h	00h	30h
Random Data Input	85h	-	85h	-
Random Read Data Output	05h	E0h	05h	E0h
Cache Read Random	00h	31h	00h	31h
Cache Read Sequential	31h	-	31h	-
Cache Read End	3Fh	-	3Fh	-
Read ID	90h	-	90h	-
Parameter Page Read (ONFI)	ECh	-	ECh	-
Read Unique ID (ONFI)	EDh	-	EDh	-
Get Features (ONFI)	EEh	-	EEh	-
Set Features (ONFI)	EFh	-	EFh	-
Reset	FFh	-	FFh	-
Page Program	80h	10h	80h	10h
Cache Program (Start)	80h	15h	80h	15h
Cache Program (End)	80h	10h	80h	10h
Block Erase	60h	D0h	60h	D0h
Status Read	70h	-	70h	-
Status Enhanced Read (ONFI)	78h	-	78h	-
Two-plane Program (ONFI)	80h-11h-80h-10h 80h-11h-80h-15h		80h-11h-80h-10h 80h-11h-80h-15h	
Two-plane Cache Program - Start/Cont.(ONFI)				
Two-plane Cache Program - End (ONFI)	80h-11h	-80h-10h	80h-11h	-80h-10h
Two-plane Block Erase (ONFI)	60h-D1h	-60h-D0h	60h-D1h-60h-D0h	



5. Status Register Comparison

Status Register bit functions are the same (**Table 5-1 Status Register Comparison**). Please refer to the Macronix datasheet for additional details.

Table 5-1. Status Register Comparison

Part Name	MX60LF8G18AC	MX60LF8G28AD	
SR[0]	Program/Cache program(page N)/ Erase	Program/Cache program(page N)/ Erase	
SK[U]	Pass or Fail	Pass or Fail	
SR[1]	Cache Program (page N-1) Pass or Fail	Cache Program (page N-1) Pass or Fail	
SR[2]	Not Used	Used Not Used	
SR[3]	Not Used	Not Used Not Used	
SR[4]	Not Used		
CDIE1	Ready/Busy for Internal Controller	Ready/Busy for Internal Controller	
SR[5] Program/Erase/Read Operation		Program/Erase/Read Operation	
SR[6]	SR[6] Ready/Busy Ready/Busy		
SR[7]	Write Protect	Write Protect	

6. Package Pin Definition

The package physical dimensions and pin definitions of the MX60LF8G18AC and the MX60LF8G28AD are identical in 48-TSOP and 63-VFBGA.

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7. Device Identification

The Device ID lengths of the MX60LF8G18AC and the MX60LF8G28AD differ by one byte. The ID of the MX60LF8G18AC begins with a one-byte Manufacturer Code followed by a four-byte Device ID. The ID of the MX60LF8G28AD begins with a one-byte Manufacturer Code followed by a five-byte Device ID. The ID codes of the MX60LF8G18AC and the MX60LF8G28AD are identical for the first three byte, but different for the 4th byte and 5th byte which indicate differences in page/spare/block size/ECC requirement and the extended 6th byte of MX60LF8G28AD for device generation (**Table 7-1 Device Identification**).

Table 7-1. Device Identification

Part Name		MX60LF8G18AC	MX60LF8G28 <i>AD</i>	
ID Code		C2h/D3h/D1h/95h/5Ah	C2h/D3h/D1h/ <i>A2h</i> /5 <i>Bh</i> /03h	
	1 st Byte	Manufacturer ID	Manufacturer ID	
	2 nd Byte	Device ID	Device ID	
		Number of Die per CE	Number of Die per CE	
		Cell Structure	Cell Structure	
		Number of Concurrently Programmed	Number of Concurrently Programmed	
	3 rd Byte	Pages	Pages	
		nterleaved operations between Multiple	Interleaved Programming between	
		die	multiple devices	
		Cache program	Cache program	
		Page Size (2KB, bit1=0 & bit0=1)	Page Size (4KB, bit1=1 & bit0=0)	
		Spare Area Size (16-byte per 512-byte),	Spare Area Size (32-byte per 512-byte),	
ID Definition		bit2=1	bit2 =0	
	4 th Byte	Sequential Read Cycle Time	Sequential Read Cycle Time	
		(bit7, bit3=1,0)	(bit7, bit3=1,0)	
		Block Size (128KB excluding spare	Block Size (256KB excluding spare	
		area, bit5=0 & bit4=1)	area, bit5=1 & bit4=0)	
		Organization	Organization	
		ECC level requirement,	ECC level requirement,	
	5 th Byte	4-bit ECC required (bit 1:0=10b)	8-bit ECC required (bit 1:0=11b)	
		Number of Planes per CE	Number of Planes per CE	
		Plane Size	Plane Size	
		Reserved	Reserved	
	6th Byte	N/A	Device Generation	

8. References

Table 8-1 shows the datasheet versions used for comparison in this application note. For the most current, detailed specification, please contact Macronix website.

Table 8-1. Datasheet Versions

Datasheet	Location	Date Issued	Revision
MX60LF8G18AC	Website	Jan. 2017	Rev. 1.1
MX60LF8G28AD	Website	Aug. 2019	Rev. 0.00

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9. Summary

The Macronix MX60LF8G18AC and MX60LF8G28AD NAND flash share the same basic Read, Program, and Erase commands and have the same package dimension and pin-outs. However, migrating to the MX60LF8G28AD may require firmware modifications to accommodate differences in page/spare/block size/ ECC requirement.

10. Part Number Cross-Reference

Table 10-1. Part Number Cross Reference

Bus Width	Voltage	Package	Part Number	Part Number
x8	3V	48-TSOP	MX60LF8G18AC-TI	MX60LF8G28AD-TI
х8	3V	63-VFBGA	MX60LF8G18AC-XKI	MX60LF8G28AD-XKI

11. Revision History

Table 11-1. Revision History

Revision No.	Description	Page	Date
REV. 1	Initial Release	ALL	Jan. 03, 2020



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